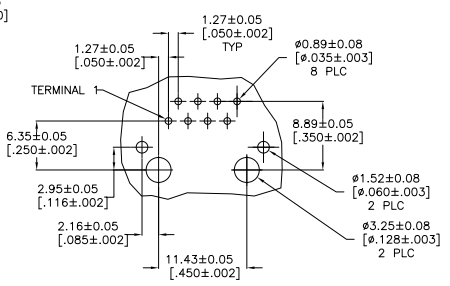
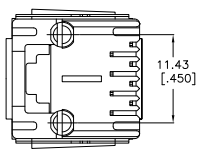
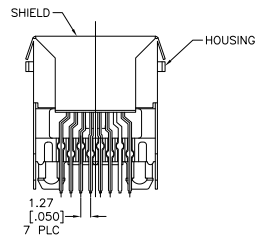
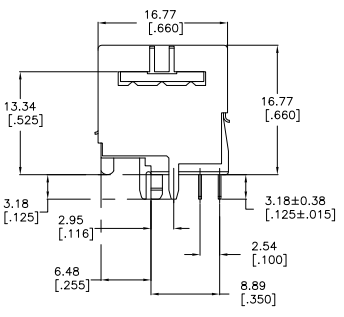
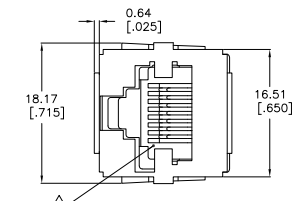
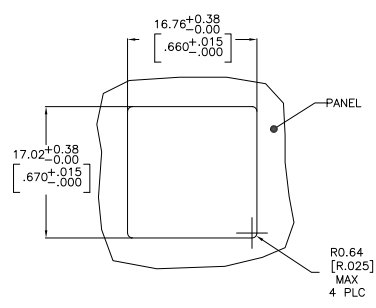


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REV	DATE	DESCRIPTION	BY	APP'D
AA	00			
C		602-07-021343		2355P107 [LAM] PR



RECOMMENDED PRINTED
 CIRCUIT BOARD LAYOUT
 COMPONENT SIDE SHOWN



RECOMMENDED PANEL
 CUTOUT

- MATERIAL:
 HOUSING - POLYESTER MOLDING COMPOUND, COLOR: BLACK
 TERMINALS - 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
 SHIELD - COPPER ZINC ALLOY PLATED WITH 3.0µm[.000120] MIN THICK REFLOWED TIN.

CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

5557730-1
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		BY: STEINBUCKER, J. J.	DATE: 10/14/03	REV: 1	DESCRIPTION: MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, KEYED WITH PANEL STOPS, PANEL AND PCB GROUNDS
UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES.	APPROVED:	BY: WESTMAN, J. J.	DATE: 10/14/03	REV: 1	DESCRIPTION: MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, KEYED WITH PANEL STOPS, PANEL AND PCB GROUNDS
SEE NOTE 1	SEE NOTE 1	DATE: 11-4-2004	REV: 1	DESCRIPTION: MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, KEYED WITH PANEL STOPS, PANEL AND PCB GROUNDS	REV: 1
CUSTOMER DRAWING		DATE: 4-1	REV: 1	DESCRIPTION: MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, KEYED WITH PANEL STOPS, PANEL AND PCB GROUNDS	REV: 1